

SOT1113-1

plastic thermal enhanced very thin quad flat package; no leads; 44 terminals

14 March 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN44
Package type industry code	HVQFN44
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	23-7-2010
Manufacturer package code	SOT1113

Table 1. Package summary

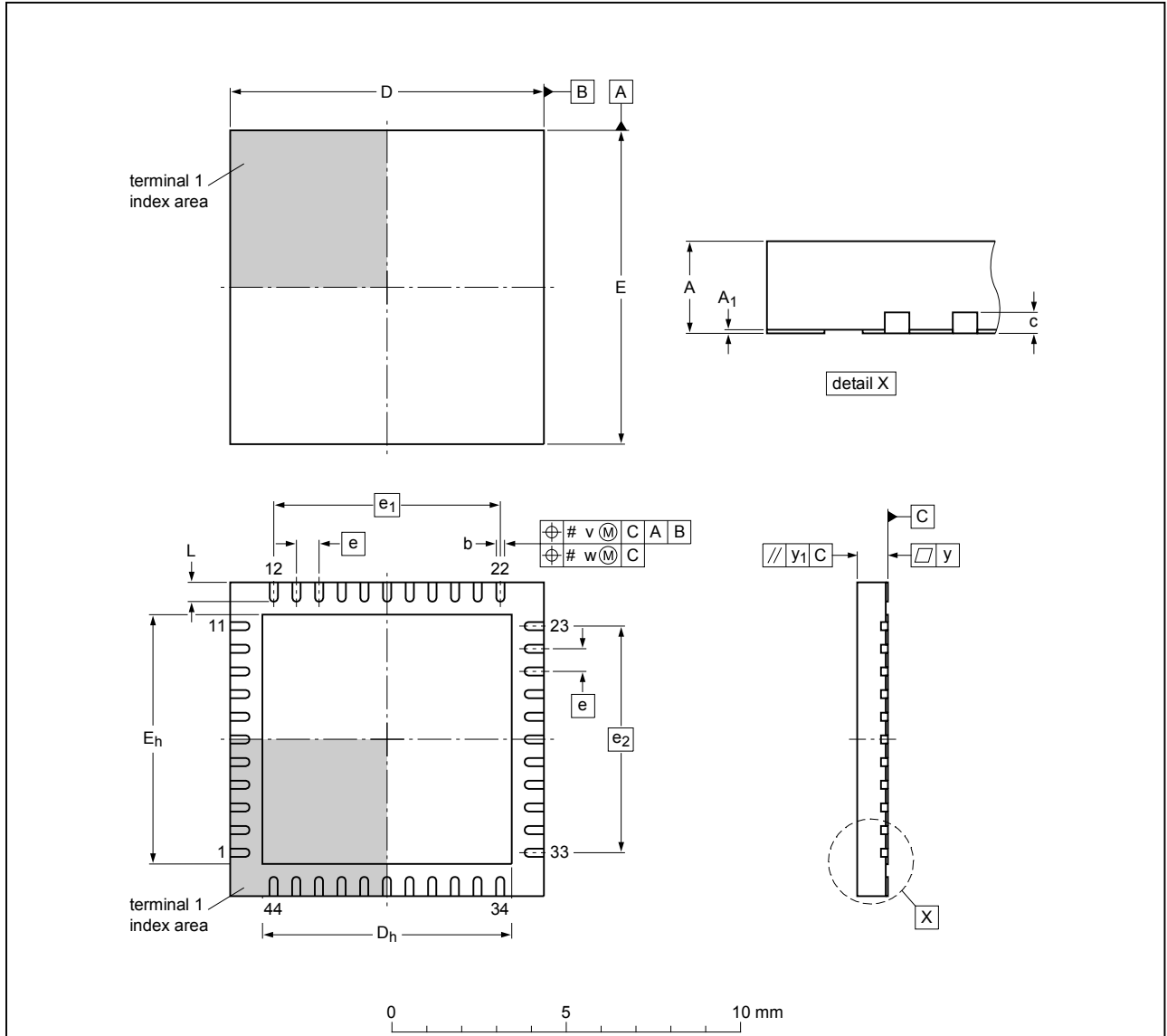
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.9	-	9	9.1	mm
E	package width	8.9	-	9	9.1	mm
A	seated height	0.8	-	0.85	1	mm
A ₂	package height	-	-	-	-	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	44	-	



2. Package outline

HVQFN44: plastic thermal enhanced very thin quad flat package; no leads
44 terminals; body 9 x 9 x 0.85 mm

SOT1113-1



Dimensions

Unit	A ⁽¹⁾	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
mm	max 1.00	0.05	0.35		9.1	7.25	9.1	7.25				0.63				
	nom 0.85	0.03	0.30	0.2	9.0	7.15	9.0	7.15	0.65	6.5	6.5	0.55	0.1	0.05	0.08	01
	min 0.80	0.00	0.25		8.9	7.05	8.9	7.05				0.47				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sof1113-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1113-1	---	---	---		09-07-17 10-07-23

Fig. 1. Package outline HVQFN44 (SOT1113-1)

3. Soldering

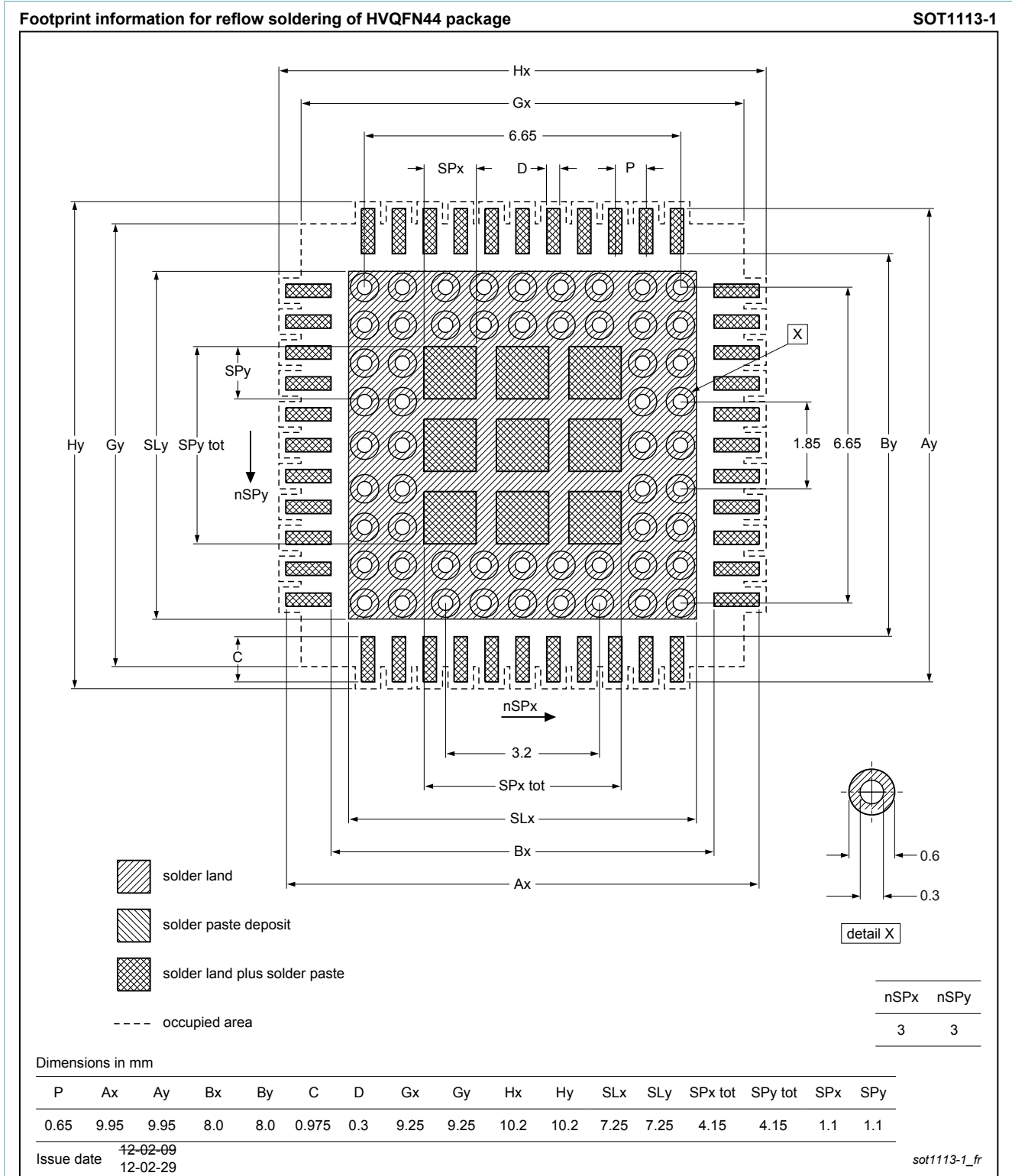


Fig. 2. Reflow soldering footprint for HVQFN44 (SOT1113-1)

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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